ISL55110_11EVAL1Z, ISL55110_11EVAL2Z

Evaluation Board User's Manual

AN1283
Rev 0.00
February 13, 2007

Before Getting Started

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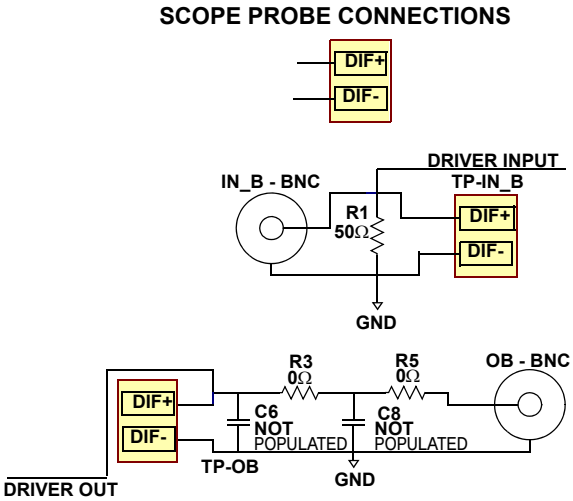

FIGURE 1. DUAL.1" SPACED PINS ARE PLACED ON THE EVALUATIONS BOARDS FOR LEADLESS ACTIVE PROBE CONNECTIONS

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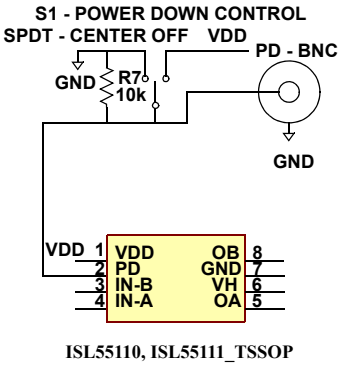

FIGURE 2. TSSOP AND QFN EVALUATION BOARDS HAVE THE SAME POWER DOWN CIRCUITRY

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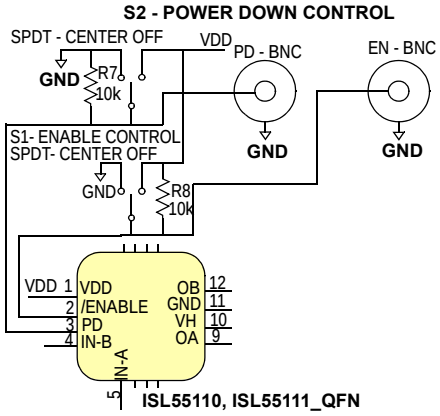

FIGURE 3. QFN PACKAGES HAVE BOTH POWER DOWN AND OUTPUT ENABLE DIGITAL INPUTS

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Please refer to the device specification for power up sequencing and current requirements. Also note that the frequency of operation of each driver will determine the current needed. There are graphs in the specification regarding current characteristics.

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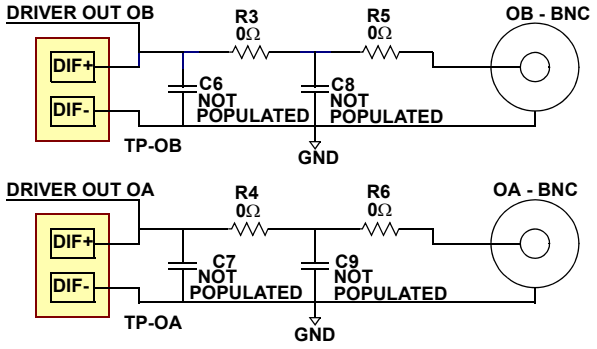

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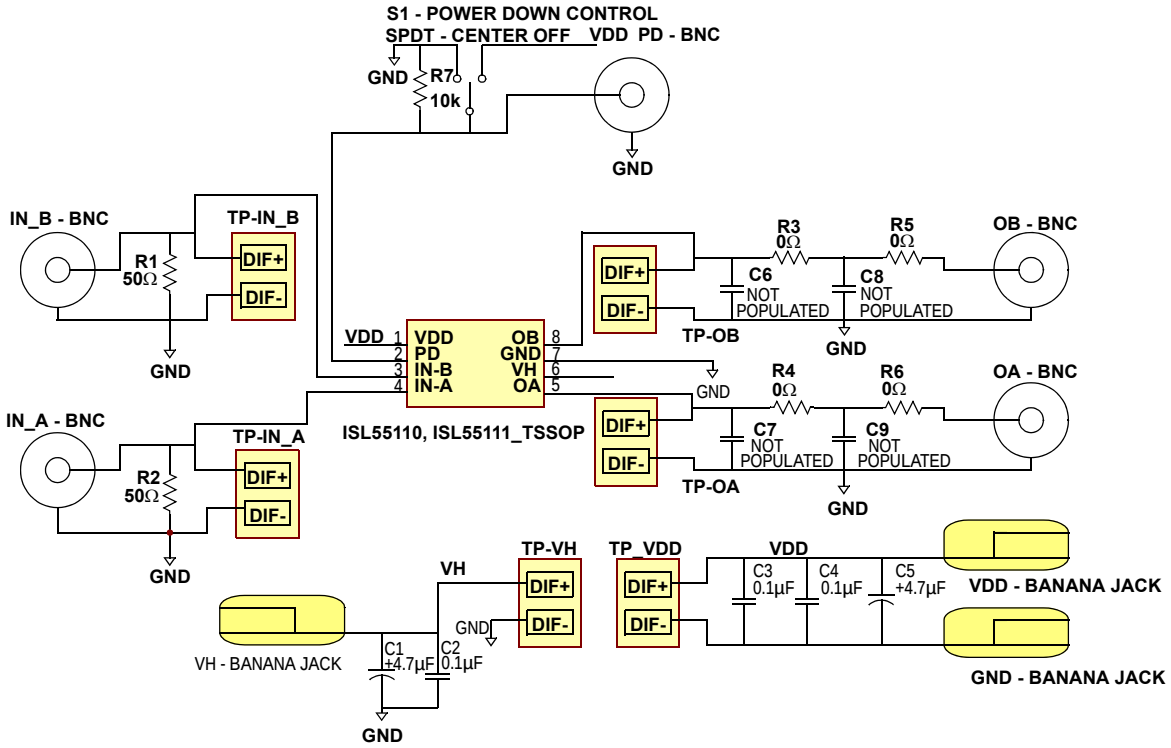

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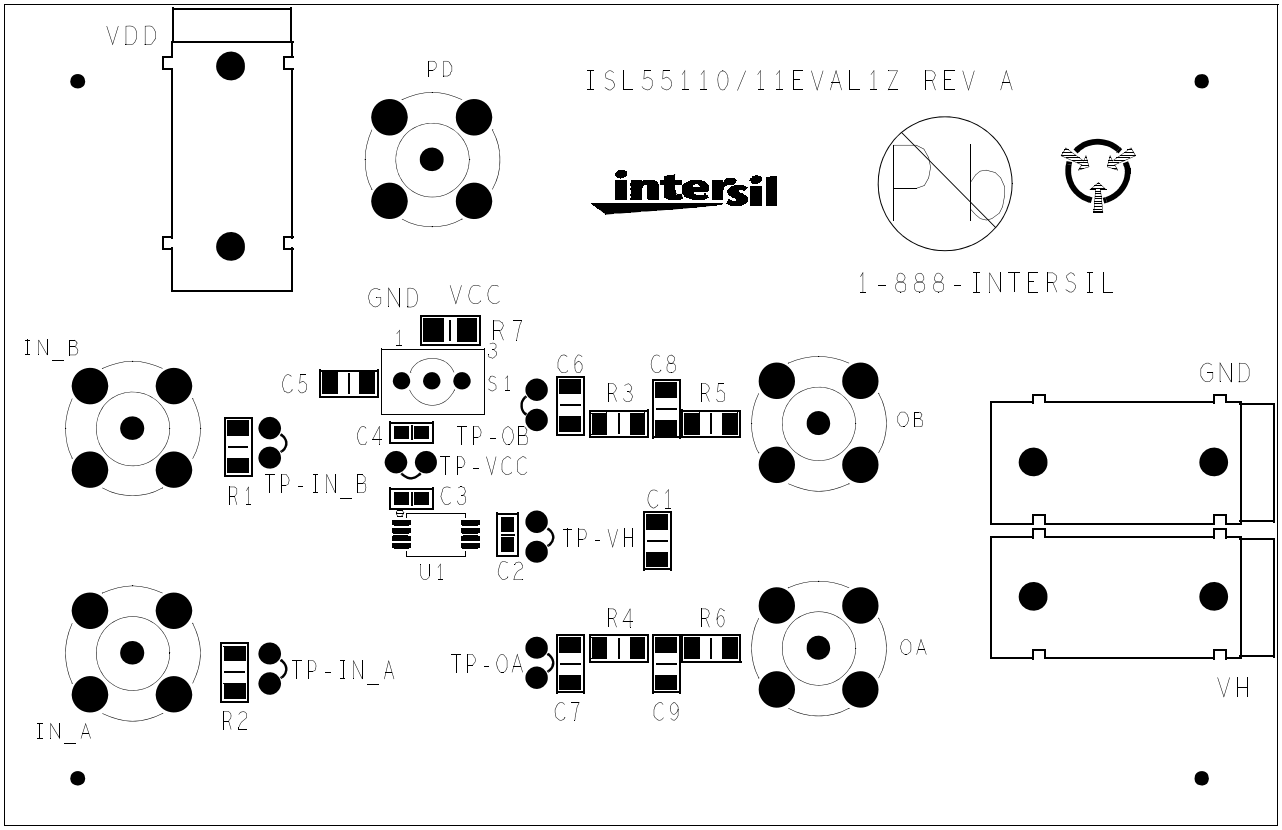
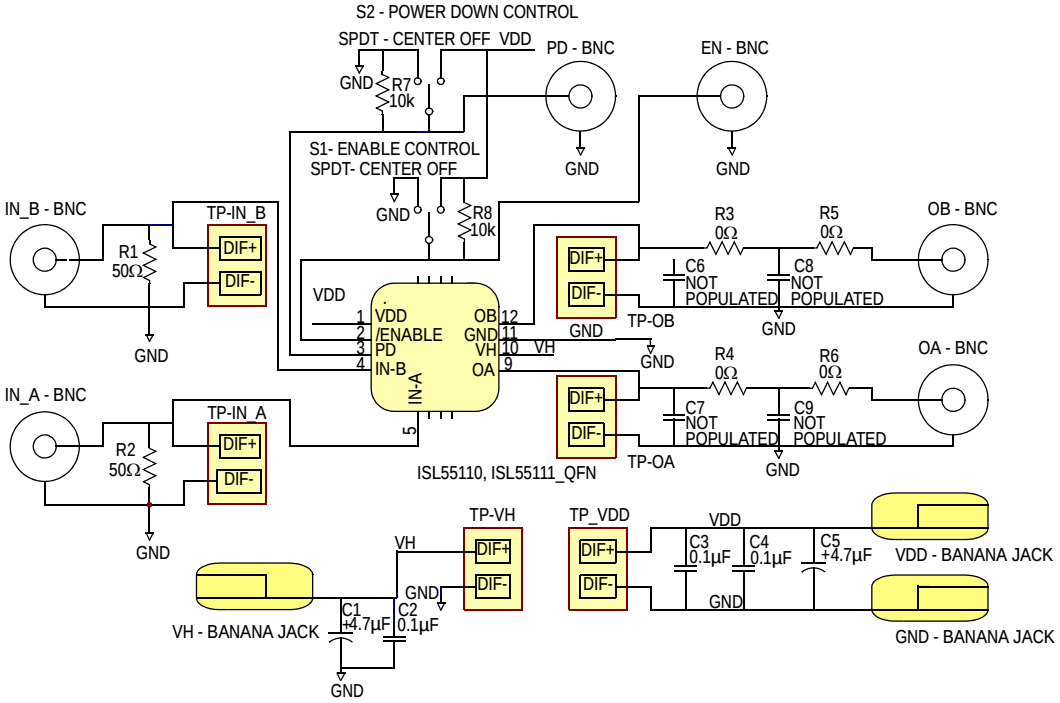


FIGURE 6. TSSOP LAYOUT



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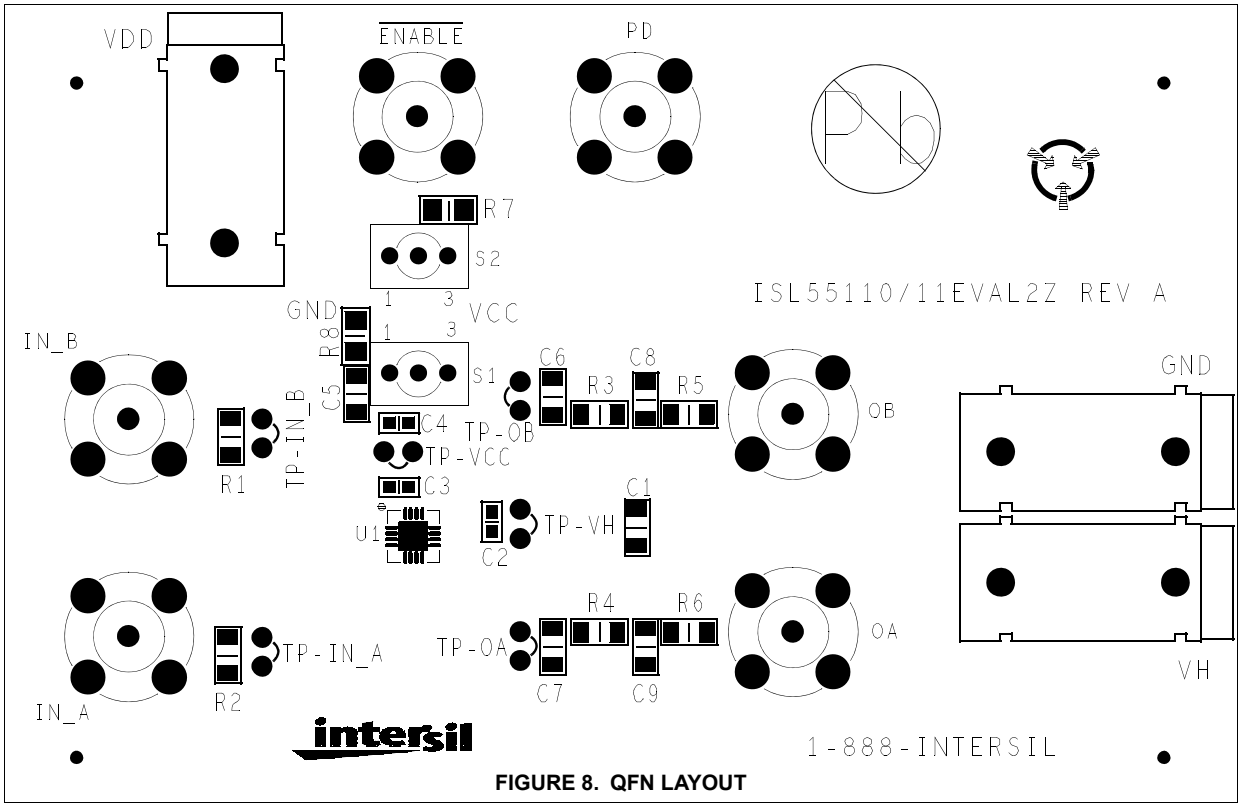

FIGURE 8. QFN LAYOUT

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Colophon 7.0

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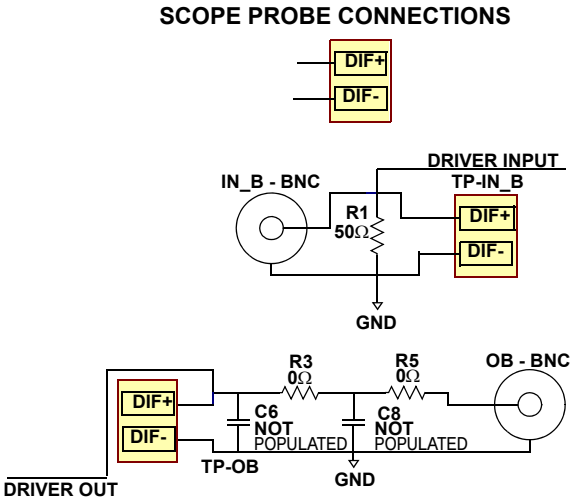

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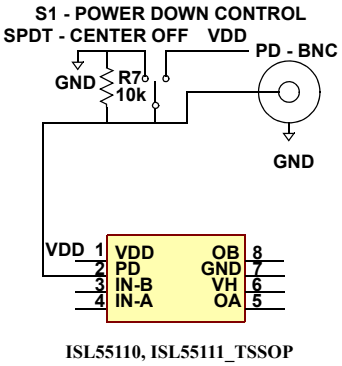

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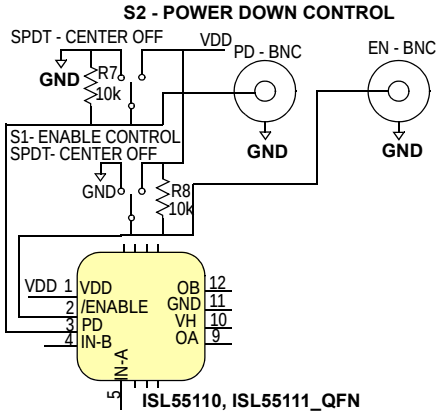

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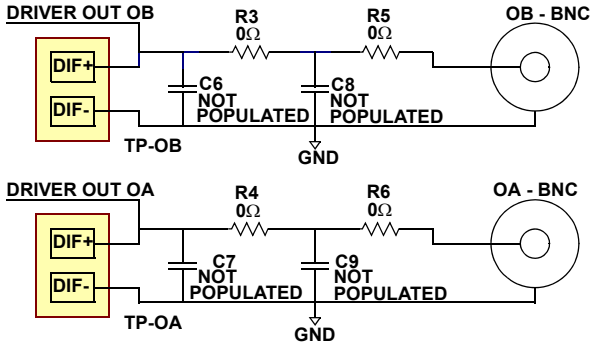

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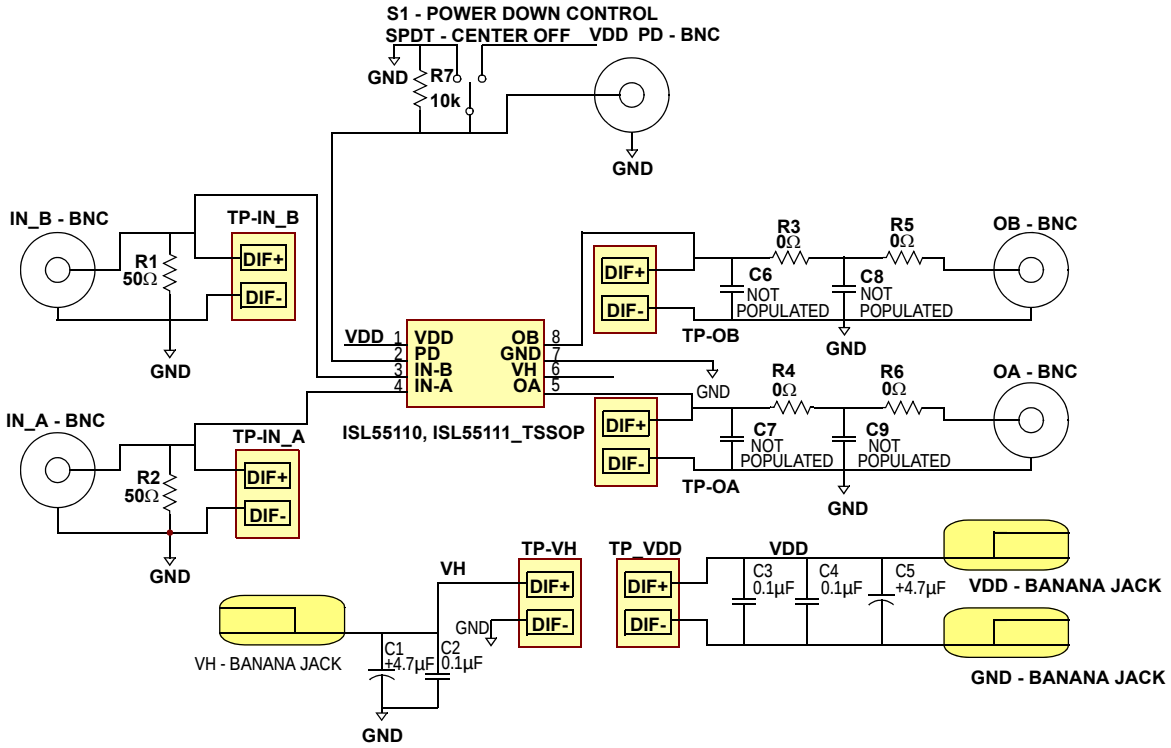

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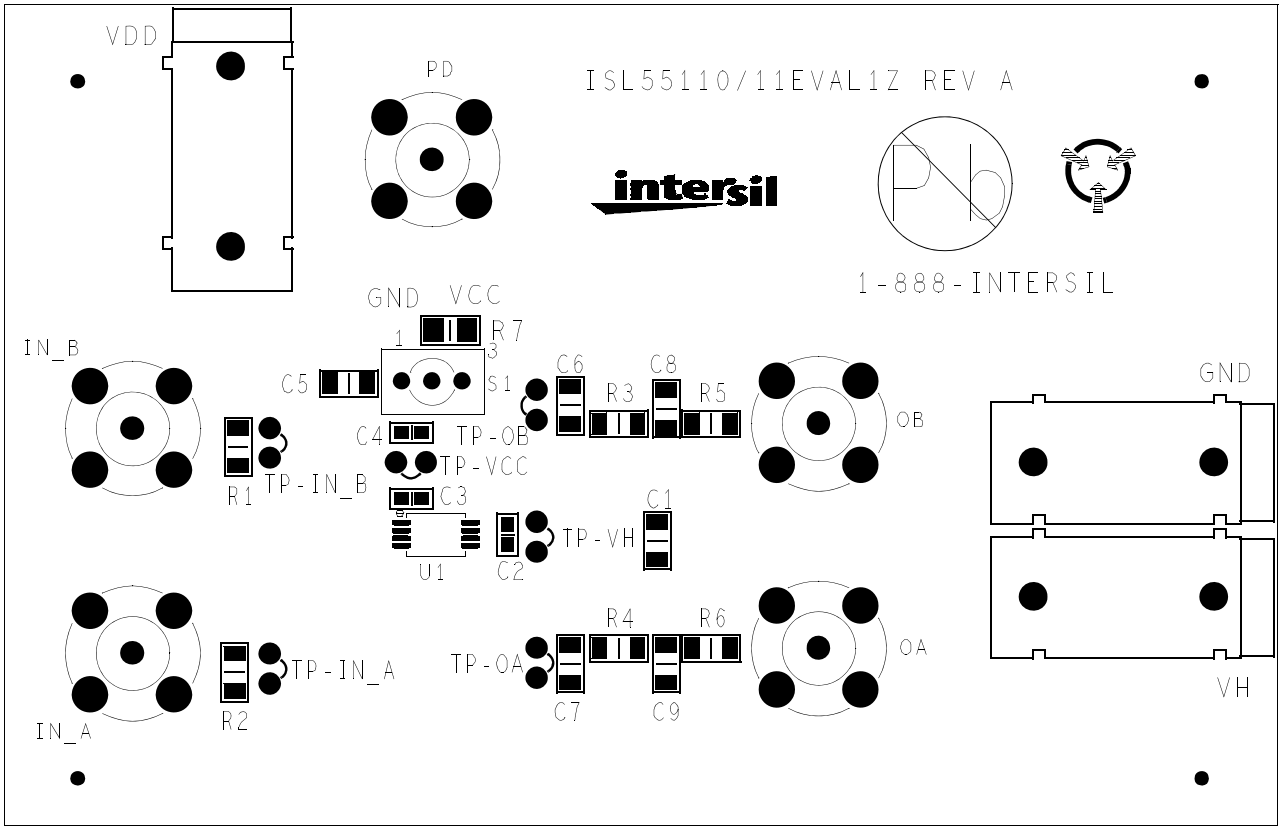

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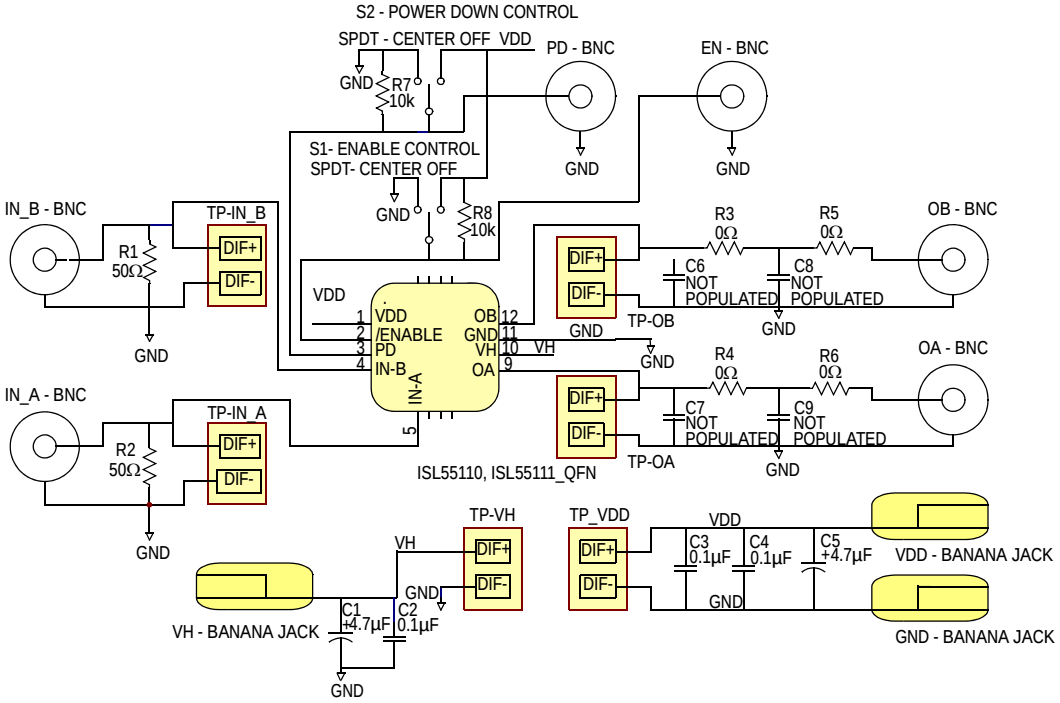

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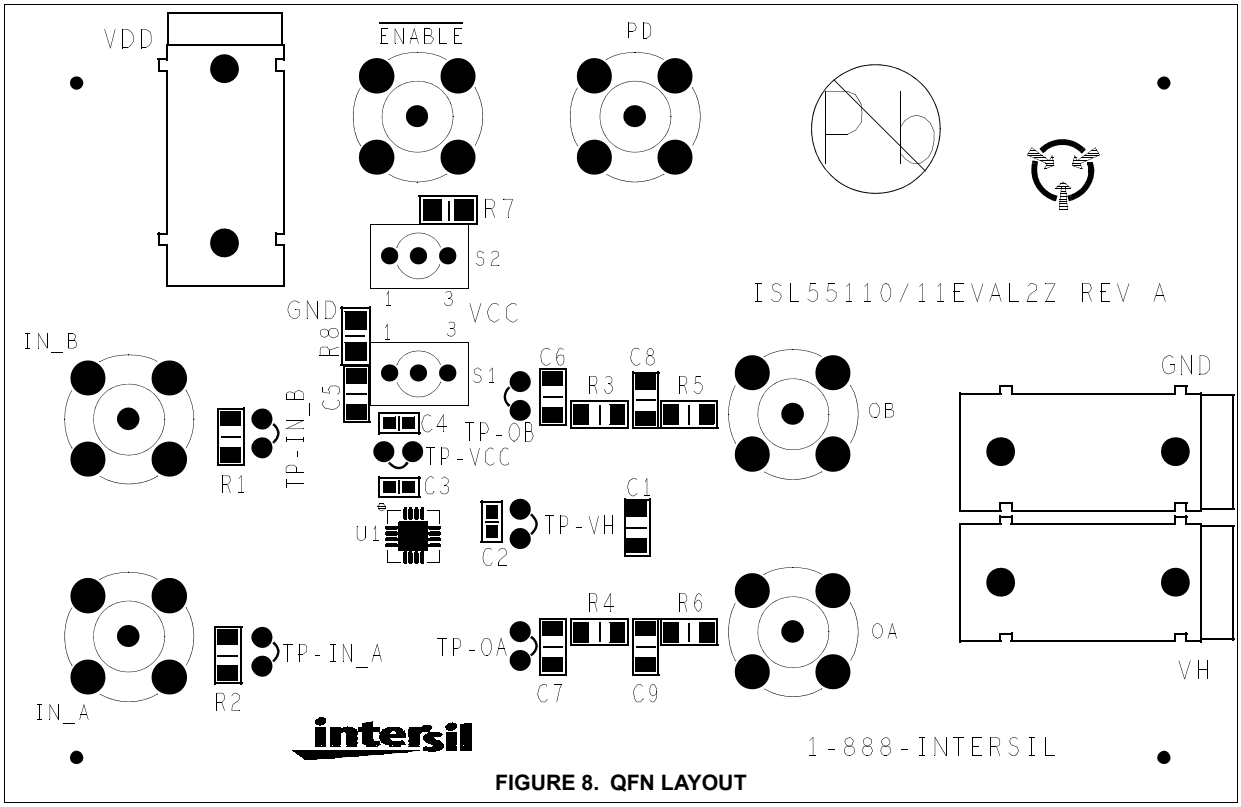

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